Power MOSFET 30V, 24mΩ, 7A, Dual N-Channel

This Power MOSFET is produced using ON Semiconductor's trench technology, which is specifically designed to minimize gate charge and low on resistance. This device is suitable for applications with low gate charge driving or low on resistance requirements.

Features

- 4V drive
- Composite type, Facilitating high-density mounting
- ESD Diode-Protected Gate
- Pb-Free, Halogen Free and RoHS compliance

Typical Applications

- LiB Protection Switch
- Motor Drive

SPECIFICATIONS

ABSOLUTE MAXIMUM RATING at Ta = 25°C (Note 1)

Parameter	Symbol	Value	Unit
Drain to Source Voltage	VDSS	30	V
Gate to Source Voltage	VGSS	±20	V
Drain Current (DC)	ID	7	Α
Drain Current (Pulse) PW ≤ 10µs, duty cycle ≤ 1%	IDP	40	Α
Power Dissipation When mounted on ceramic substrate (900mm²×0.8mm) 1unit	PD	1.3	W
Total Dissipation When mounted on ceramic substrate (900mm²×0.8mm)	PT	1.5	W
Junction Temperature	Tj	150	°C
Storage Temperature	Tstg	-55 to +150	°C

Note 1: Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Value	Unit			
Junction to Ambient						
When mounted on ceramic substrate	$R_{\theta JA}$	96.1	°C/W			
(900mm ² × 0.8mm) 1unit						

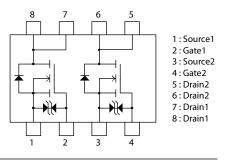


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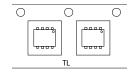
VDSS	R _{DS} (on) Max	ID Max
	24mΩ@ 10V	
30V	41mΩ@ 4.5V	7A
	55mΩ@ 4V	

ELECTRICAL CONNECTION N-Channel



PACKING TYPE : TL

MARKING





ORDERING INFORMATION

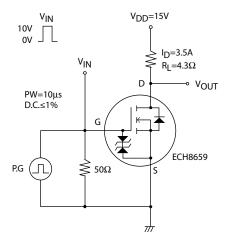
See detailed ordering and shipping information on page 5 of this data sheet.

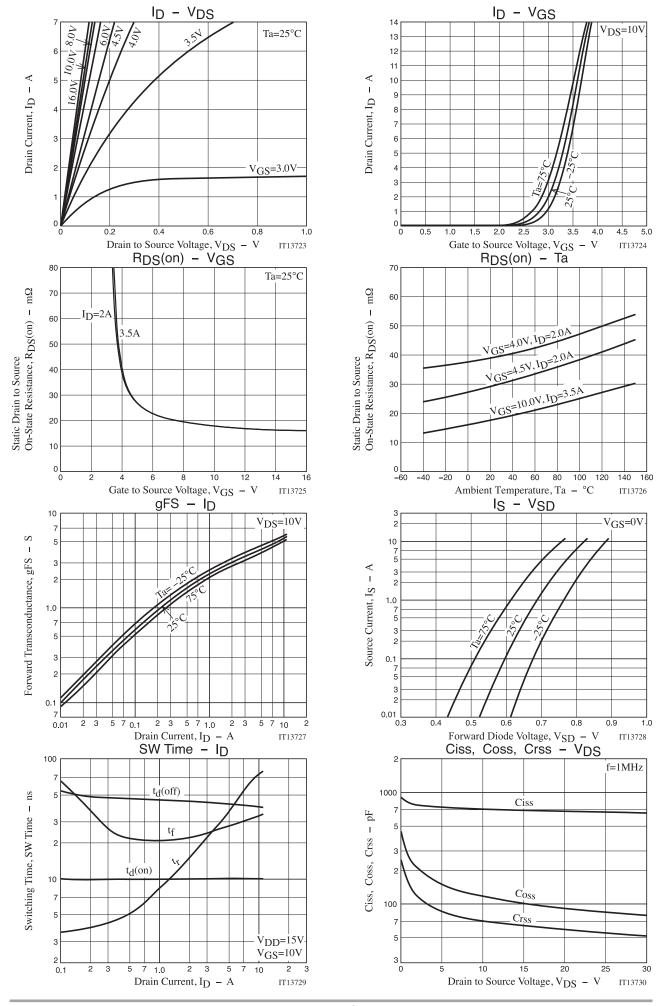
ELECTRICAL CHARACTERISTICS at Ta = 25°C (Note 2)

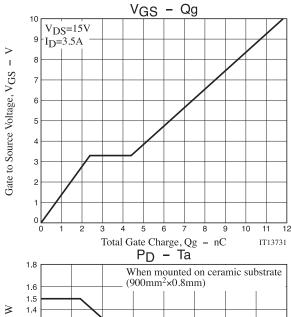
			Value				
Parameter	Symbol	Conditions	min	typ	max	Unit	
Drain to Source Breakdown Voltage	V(BR)DSS	ID=1mA, VGS=0V	30			V	
Zero-Gate Voltage Drain Current	IDSS	V _{DS} =30V, V _{GS} =0V			1	μΑ	
Gate to Source Leakage Current	IGSS	V _{GS} =±16V, V _{DS} =0V			±10	μА	
Gate Threshold Voltage	VGS(th)	V _{DS} =10V, I _D =1mA	1.2		2.6	V	
Forward Transconductance	gFS .	V _{DS} =10V, I _D =3.5A	2.2	3.7		S	
	R _{DS} (on)1	I _D =3.5A, V _{GS} =10V		18	24	mΩ	
Static Drain to Source On-State	R _{DS} (on)2	I _D =2A, V _G S=4.5V		29	41	mΩ	
Resistance	RDS(on)3	I _D =2A, V _{GS} =4V		39	55	mΩ	
Input Capacitance	Ciss			710		pF	
Output Capacitance	Coss	V _{DS} =10V, f=1MHz		120		pF	
Reverse Transfer Capacitance	Crss			72		pF	
Turn-ON Delay Time	t _d (on)			10		ns	
Rise Time	t _r			25		ns	
Turn-OFF Delay Time	t _d (off)	See specified Test Circuit		43		ns	
Fall Time	tf			25		ns	
Total Gate Charge	Qg			11.8		nC	
Gate to Source Charge	Qgs	V _{DS} =15V, V _{GS} =10V, I _D =3.5A		2.4		nC	
Gate to Drain "Miller" Charge	Qgd			2.0		nC	
Forward Diode Voltage	V _{SD}	IS=7A, VGS=0V		0.79	1.2	V	

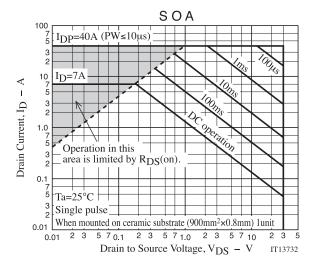
Note 2 : Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

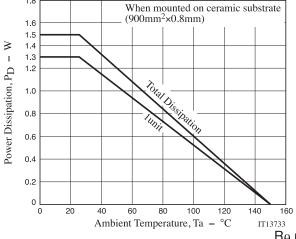
Switching Time Test Circuit

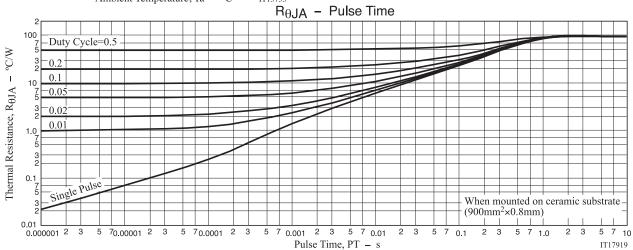






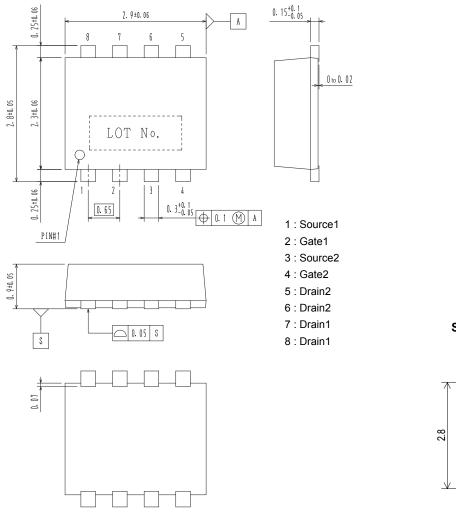




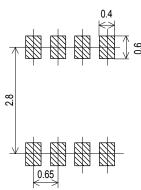


PACKAGE DIMENSIONS

unit: mm SOT-28FL/ECH8 CASE 318BF ISSUE O



Recommended Soldering Footprint



ORDERING INFORMATION

Device	Marking	Package	Shipping (Qty / Packing)	
ECH8659-TL-H	TE	SOT-28FL / ECH8	3,000 / Tape & Reel	
ECH8659-TL-W	TE	(Pb-Free / Halogen Free)		

[†] For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D. http://www.onsemi.com/pub_link/Collateral/BRD8011-D.PDF

Note on usage: Since the ECH8659 is a MOSFET product, please avoid using this device in the vicinity of highly charged objects.

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